

L Number	Hits	Search Text	DB	Time stamp
1	417	257/666.ccls. and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 17:34
2	345	(257/666.ccls. and ceramic) and (@ad<20000420)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 17:35
3	78	257/666.ccls. and (ceramic near substrate) and (lead or leads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:08
4	66	(257/666.ccls. and (ceramic near substrate) and (lead or leads)) and (@ad<20000420)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:08
5	26661	(carrier and ((lead or load or terminal or terminals or leads or loads) with (housing or case or house))) and (@ad<20000420)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:01
6	362	((carrier and ((lead or load or terminal or terminals or leads or loads) with (housing or case or house))) and (@ad<20000420)) and (ceramic near substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:03
7	69	((carrier and ((lead or load or terminal or terminals or leads or loads) with (housing or case or house))) and (@ad<20000420)) and (ceramic near substrate)) and (switch or switching or transistor) and (@ad<20000420)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:04
8	84	257/666.ccls. and (ceramic near substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:10
9	71	(257/666.ccls. and (ceramic near substrate)) and (@ad<20000420)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:11
10	0	257/666.ccls. and (ceramic near interposer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:10
11	103	257/666.ccls. and (chip with ceramic) and (@ad<20000420)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:11
12	103	(257/666.ccls. and (chip with ceramic) and (@ad<20000420)) and (@ad<20000420)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:25
13	3310	(ceramic near substrate) and (carrier or plate) and (housing or house or case) and (leads or lead or loads or load) and (@ad<20000420)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 19:07

14	2038	((ceramic near substrate) and (carrier or plate) and (housing or house or case) and (leads or lead or loads or load) and (@ad<20000420)) and (chip or chips or transistor or transistors or switch or switches)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:29
15	66	((((ceramic near substrate) and (carrier or plate) and (housing or house or case) and (leads or lead or loads or load) and (@ad<20000420)) and (chip or chips or transistor or transistors or switch or switches)) and (potential with (leads or lead or loads or load))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 18:30
16	26	257/666.ccls. and ((ceramic near substrate) and (carrier or plate) and (housing or house or case) and (leads or lead or loads or load) and (@ad<20000420))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/13 19:09